

Absolute Maximum Ratings		Values	Units
Symbol	Conditions ¹⁾		
V _{CES}		1000	V
V _{GCR}	R _{GE} = 20 kΩ	1000	V
I _C	T _{case} = 70 °C	50	A
I _{CM}	T _{case} = 70 °C	100	A
V _{GES}		± 20	V
P _{tot}	per IGBT, T _{case} = 25 °C	400	W
T _J , T _{Stg}		-55 ... +150	°C
V _{Isol}	AC, 1 min, 200 µA	2500	V
humidity	DIN 40 040	Class F	
climate	DIN IEC 68 T.1	55/150/56	
Inverse Diode, Free-Wheeling Diode			
I _F = -I _C	T _{case} = 70 °C	50	A
I _{FM} = -I _{CM}	T _{case} = 70 °C	100	A

Characteristics		min.	typ.	max.	Units
Symbol	Conditions ¹⁾				
V _{(BR)CES}	V _{GE} = 0, I _C = 1 mA	1000	-	-	V
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 4 mA	4,5	5,5	7	V
I _{CES}	V _{GE} = 0, } T _J = 25 °C	-	0,01	1	mA
	V _{CE} = 1000 V } T _J = 125 °C	-	-	4	mA
I _{GES}	V _{GE} = 20 V, V _{CE} = 0	-	-	100	nA
V _{CESat}	V _{GE} = 15 V, I _C = 50 A	-	3,5	5	V
g _{fs}	V _{CE} = 20 V, I _C = 50 A	22	28	-	S
C _{CHC}	per IGBT	-	-	100	pF
C _{ies}	V _{GE} = 0; V _{CE} = 25 V	-	16	-	nF
C _{oes}	f = 1 MHz	-	640	-	pF
C _{res}		-	200	-	pF
L _{CE}		-	-	20	nH
t _{d(on)}	{ V _{CC} = 600 V I _C = 50 A V _{GE} = 15 V R _{eon} = R _{gooff} = 3,3 Ω T _J = 125 °C see fig. 21	-	100 ³⁾	-	ns
t _r		-	300 ³⁾	-	ns
t _{d(off)}		-	400 ^{3)/400⁴⁾}	-	ns
t _f		-	500 ^{3)/250⁴⁾}	-	ns
W _{off} 12		-	0,9 ⁴⁾	-	mWs
W _{off} 23		-	1,3 ⁴⁾	-	mWs
Inverse Diode, Free-Wheeling Diode					
V _{EC}	I _F = 50 A, V _{GE} = 0; (T _J = 125 °C)	-	1,8 (1,6)	-	V
t _{rr}	T _J = 25 °C ²⁾	-	-	-	ns
	T _J = 125 °C ²⁾	-	200	-	ns
Q _{rr}	T _J = 25/125 °C ²⁾	-	2/9	-	µC
I _{RRM}	T _J = 25/125 °C ²⁾	-	-	-	A
Thermal Characteristics					
R _{thjc}	per IGBT	-	-	0,31	°C/W
R _{thjc}	per diode	-	-	1,0	°C/W
R _{thch}	per module	-	-	0,05	°C/W

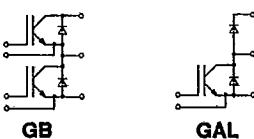
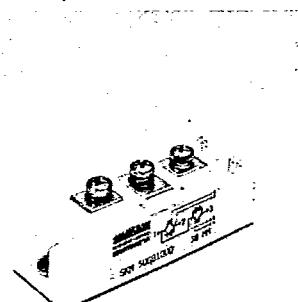
Mechanical Data		D 33	D 27
M ₁	to heatsink, SI Units	4	
	to heatsink, US Units	35	
M ₂	for terminals, SI Units	2,5	
	for terminals, US Units	22	
a		-	5x9,81
w		-	250
Case	→ page B 6 – 103	GAL	
		GB	

SEMITRANS® M IGBT Modules

SKM 50 GB 100 D

SKM 50 GAL 100 D

Preliminary Data



Features

- MOS input (voltage controlled)
- N channel
- Low saturation voltage
- Very low tail current
- Low temperature sensitivity
- Breakdown proof
- High short circuit capability
- No latch-up
- Fast inverse diodes
- Isolated copper baseplate
- Large clearances and creepage distances
- UL recognized, file no. E 63 532

Typical Applications

- Switched mode power supplies
- DC servo and robot drives
- Self-commutated inverters
- DC choppers
- AC motor speed control
- Inductive heating
- Uninterruptible power supplies
- Electronic welders
- General power switching applications
- Pulse frequencies above 15 kHz

IGBT – Insulated Gate Bipolar Transistor

1) T_{case} = 25 °C, unless otherwise specified

2) I_F = -I_C, V_R = 600 V,
-di_F/dt = 800 A/µs, V_{GE} = 0

3) resistive load

4) inductive load

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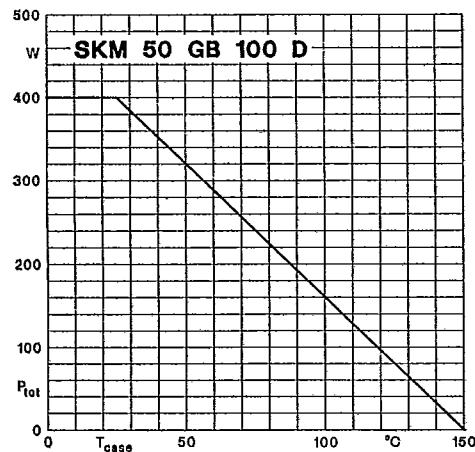


Fig. 1 Rated power dissipation vs. temperature

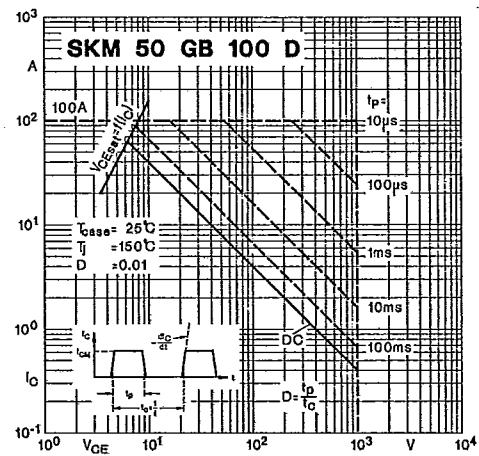


Fig. 2 Maximum safe operating area

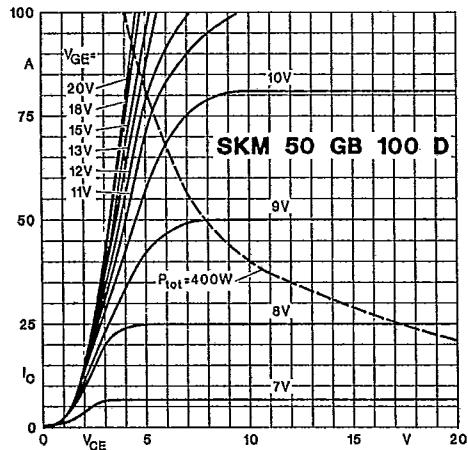


Fig. 15 Output characteristic

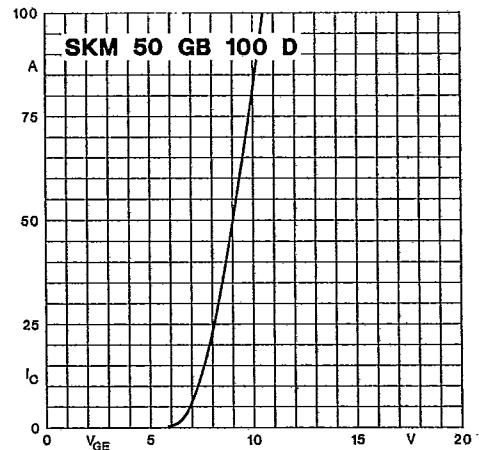


Fig. 16 Transfer characteristic

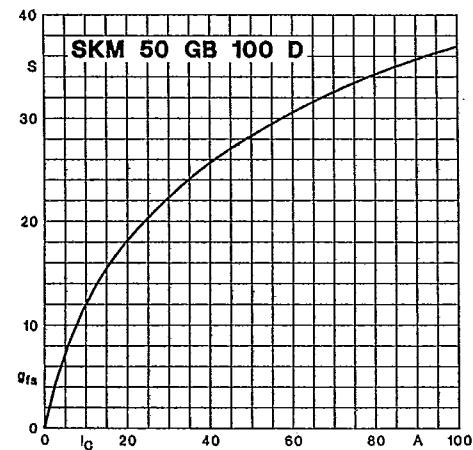


Fig. 17 Forward transconductance

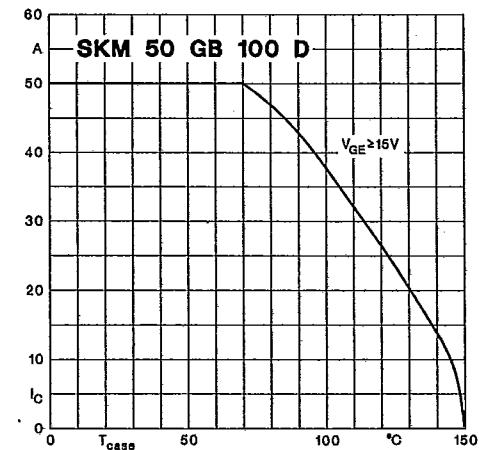


Fig. 18 Rated current vs. temperature

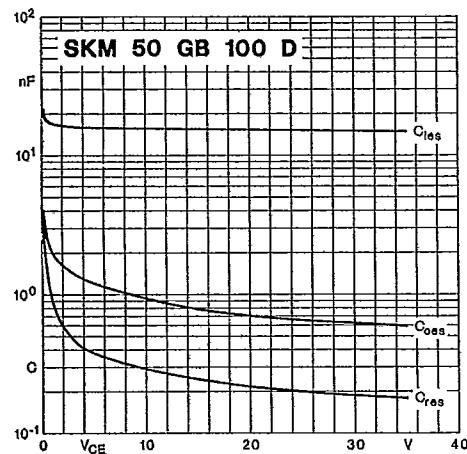


Fig. 19 Capacitances vs. collector-emitter voltage

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Fig. 20 Gate charge characteristic

Fig. 11 Diode forward characteristic

Fig. 12 Diode recovered charge

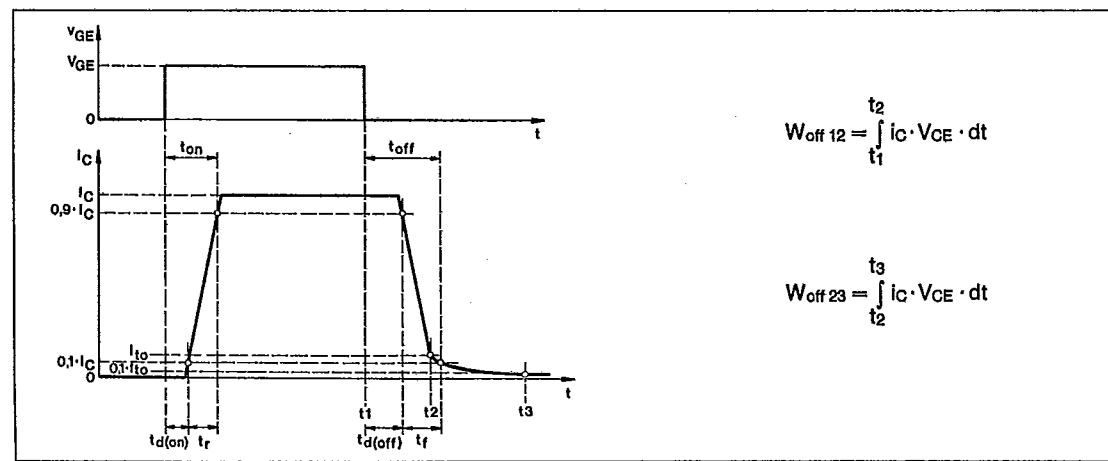


Fig. 21 Switching times and turn-off energies

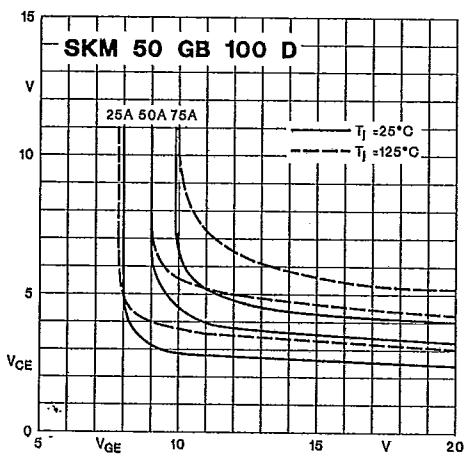


Fig. 22 Saturation characteristics

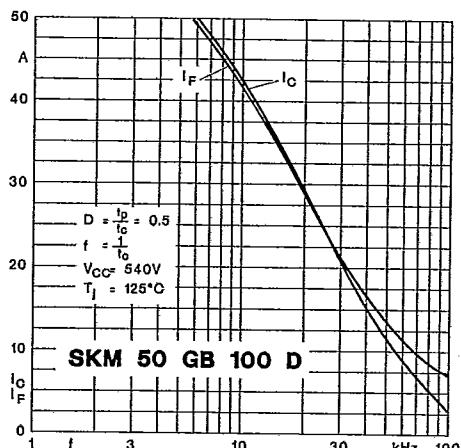


Fig. 23 Current ratings vs. pulse frequency

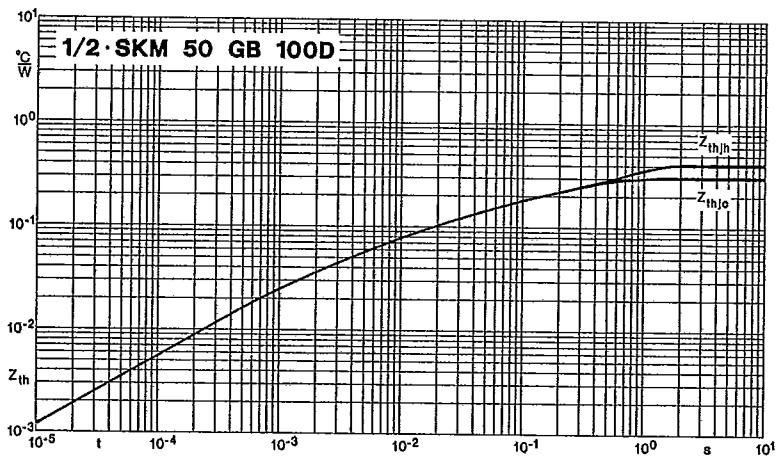


Fig. 25 Transient thermal impedance

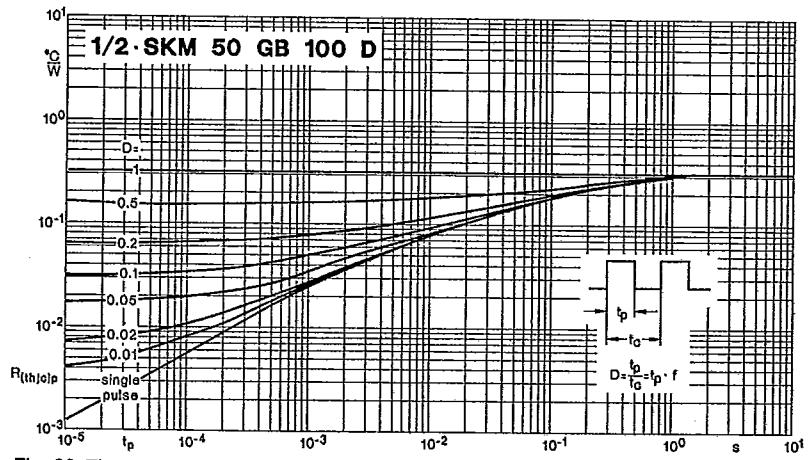


Fig. 26 Thermal impedance under pulse conditions